

IMPACT

TE Internal #: 2007703-1 High Speed Backplane Connectors, Board-to-Board, 90 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 10 Column, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Connectors



Connector System: Board-to-Board

Number of Positions: 90

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Keyed

Features

Product Type Features

Signal Arrangement

Connector System

PCB Connector Assembly Type

Differential

Board-to-Board

PCB Mount Receptacle

Shroud Style	Unshrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Ground Positions	30
Number of Pairs	30
Stackable	No
Number of Signal Positions	60
Number of Positions	90
Number of Rows	9
Number of Columns	10
PCB Mount Orientation	Right Angle
Guide Location	Left
Electrical Characteristics	
Impedance	100 Ω

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Operating Voltage	30 VAC
Signal Characteristics	
Number of Differential Pairs per Column	3
Data Rate	20 – 25 Gb/s
Contact Features	
Contact Layout	Inline
PCB Contact Termination Area Plating Material Thickness	1.27 μm[50 μin]
Contact Type	Socket
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Mating Area Plating Material	Gold
Contact Shape & Form	Dual Beam
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A
Termination Features	
Termination Post & Tail Length	1.2 mm[.047 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
PCB Mount Alignment Type	Locating Posts
Mating Retention	Without
Guide Hardware	With
PCB Mount Retention	With
PCB Mount Retention Type	Action/Compliant Tail & Screw
Mating Alignment	With
Mating Alignment Type	Keyed
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	0
Housing Material	LCP - GF (Liquid Crystal Polymer)
Housing Color	Black

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Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	19 mm[1.047 in]
Connector Height	13.3 mm[.524 in]
Connector Width	24.2 mm[.953 in]
PCB Thickness (Recommended)	1 mm
PCB Hole Diameter	.39 mm[.015 in]
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL File Number	E28476
UL Rating	Recognized
CSA Certified	Yes
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Method

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

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Product Compliance Disclaimer

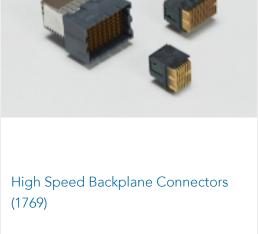
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | IMPACT



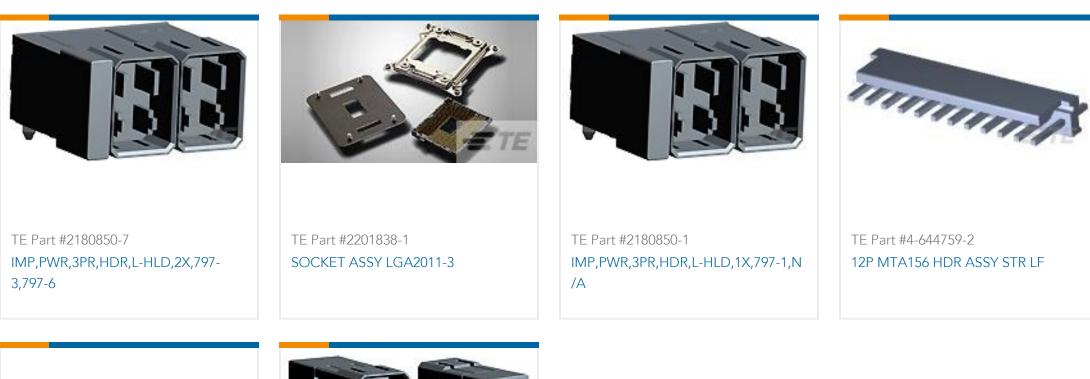


Customers Also Bought



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TE Part #2169802-4 IMP,Power,4PR,R/A,Hdr,5.7,6.9Tin

Documents

Product Drawings IMP100S,R,RA3P10C,LG,39

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_2007703-1_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2007703-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2007703-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages 7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

High Speed Backplane Interconnect Solutions Brochure 1654263-1

English

Product Specifications

Application Specification

English

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Product Environmental Compliance MD_2007703-1_112120132236_dmtec

English

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English

Agency Approvals Agency Approval Document

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